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# FSA2467 0.4Ω Low-Voltage Dual DPDT Analog Switch

#### **Features**

- Typical 0.4Ω On Resistance (R<sub>ON</sub>) for +2.7V Supply
- Features Less then12μA IccT Current when Sn Input is Lower than V<sub>CC</sub>
- 0.25Ω Maximum R<sub>ON</sub> Flatness for +2.7V Supply
- 3 x 3mm 16-Lead MLP Package
- 1.8x2.6mm 16-Lead UMLP Package
- Broad V<sub>CC</sub> Operating Range
- Low THD (0.02% Typical for 32Ω Load)

# **Applications**

- Cell Phone
- PDA
- Portable Media Player

### **Description**

The FSA2467 is a dual Double-Pole, Double-Throw (DPDT) analog switch. The FSA2467 operates from a single 1.65V to 4.3V supply. The FSA2467 features an ultra-low on resistance of  $0.4\Omega$  at a +2.7V supply and 25°C. This device is fabricated with sub-micron CMOS technology to achieve fast switching speeds and is designed for break-before-make operation.

FSA2467 features very low quiescent current even when the control voltage is lower than the  $V_{\text{CC}}$  supply. This feature allows mobile handset applications direct interface with baseband processor general-purpose  $I/O_{\text{S}}$ 

# **Ordering Information**

Part Number	Top Mark	Package Description
FSA2467MPX	FSA 2467	16-lead Molded Leadless Package (MLP), JEDEC MO-220, 3 x 3mm Square
FSA2467UMX	GC	16-lead Ultrathin Molded Leadless Package (UMLP), 1.8 x 2.6mm

# **Application Diagram**

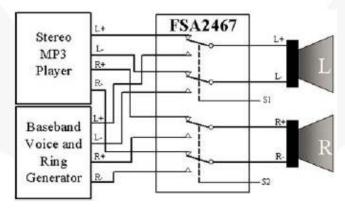


Figure 1. Application Diagram

# **Pin Assignments**

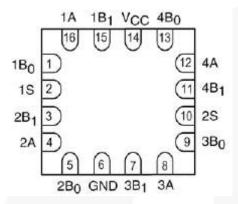


Figure 2. MLP (Top Through View)

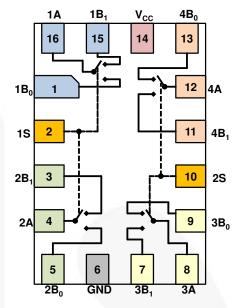


Figure 3. UMLP (Top View)

### **Truth Table**

Control Inputs	Function
LOW	nB <sub>0</sub> Connected to nA
HIGH	nB <sub>1</sub> Connected to nA

# **Pin Descriptions**

Name	Function
$nA$ , $nB_0$ , $nB_1$	Data Ports
nS	Control Input

# **Analog Symbol**

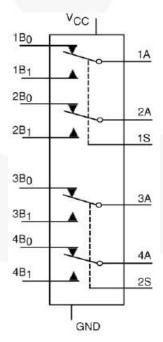


Figure 4. Analog Symbol

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parame	ter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage		-0.5	5.0	V
Vs	Switch Voltage		-0.5	V <sub>CC</sub> +0.3	V
V <sub>IN</sub>	Input Voltage		-0.5	5.0	V
I <sub>IK</sub>	Input Diode Current		-50		mA
I <sub>SW</sub>	Switch Current			350	mA
I <sub>SWPEAK</sub>	Peak Switch Current (Pulsed at 1ms	duration, <10% Duty Cycle)		500	mA
T <sub>STG</sub>	Storage Temperature Range		-65	+150	ºC
$T_J$	Junction Temperature		1	+150	ºC
TL	Lead Temperature, Soldering 10 Sec		+260	ºC	
ESD	Electrostatic Discharge Capability	Human Body Model, JESD22-A114	(	5.5	kV

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	1.65	4.30	٧
V <sub>IN</sub>	Control Input Voltage <sup>(1)</sup>	0	V <sub>CC</sub>	٧
Vs	Switch Input Voltage	0	V <sub>CC</sub>	٧
T <sub>A</sub>	Operating Temperature	-40	+85	ōС

#### Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

#### **DC Electrical Characteristics**

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Condition	V <sub>cc</sub> (V)	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C		Unit	
<b>-</b> ,	T didiliotoi	Condition	•66(•)	Min.	Тур.	Max.	Min	Max.	Ome	
			4.3				1.4			
$V_{IH}$	Input Voltage High		2.7 to 3.6				1.3		V	
V IH	Imput Voltage Flight		2.3 to 2.7				1.1		·	
			1.65 to 1.95				0.9			
			4.3					0.7		
W	Innut Valtage Levy		2.7 to 3.6					0.5	V	
$V_{IL}$	Input Voltage Low		2.3 to 2.7					0.4	V	
			1.65 to 1.95		- //			0.4		
I <sub>IN</sub>	Control Input Leakage	V <sub>IN</sub> =0V to V <sub>CC</sub>	1.65 to 4.30				-0.5	0.5	μΑ	
I <sub>NO(OFF)</sub>	Off Leakage Current of	nA=0.3V, V <sub>CC</sub> -0.3V	4.05 . 4.00	-10		40		1		
	Port nB <sub>0</sub> and nB <sub>1</sub>	$nB_0$ or $nB_1$ =0.3V, $V_{CC}$ -0.3V or floating	B <sub>1</sub> =0.3V, V <sub>CC</sub> - floating			10	-50	50	nA	
On Leakage Curr	On Leakage Current of	nA=0.3V,V <sub>CC</sub> -0.3V	1.05 4- 4.00			10	F0	F0	0	
I <sub>A(ON)</sub>	Port A	nB <sub>0</sub> or nB <sub>1</sub> =0.3V, V <sub>CC</sub> -0.3V or Floating	1.95 to 4.30	-10		10	-50	50	nA	
		I <sub>OUT</sub> =100mA	4.3		0.4			0.6		
	Switch On	nB <sub>0</sub> or nB <sub>1</sub> =0V,0.8V, 1.8V,2.7V	2.7		0.4			0.6		
R <sub>on</sub>	Switch On Resistance <sup>(2)</sup>	I <sub>OUT</sub> =100mA, nB <sub>0</sub> or nB <sub>1</sub> =0V,0.7V, 1.2V, 2.3V	2.3	0.55				0.95	Ω	
		$I_{OUT}$ =100mA, $nB_0$ or $nB_1$ =1.0V	1.8	0.8				2.0		
$\Delta R_{ m ON}$	On Resistance Matching Between	$I_{OUT}$ =100mA, $nB_0$ or $nB_1$ =0.8V	2.7	0.04	1			0.10	Ω	
ZI VON	Channels <sup>(3)</sup>	$I_{OUT}$ =100mA, nB <sub>0</sub> or nB <sub>1</sub> =0.7V						0.10		
D	On Resistance	I <sub>OUT</sub> =100mA, B <sub>0</sub> or	2.7					0.25		
R <sub>FLAT(ON)</sub>	Flatness <sup>(4)</sup>	nB <sub>1</sub> =0V to V <sub>CC</sub>	2.3					0.3	Ω	
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> =0V to V <sub>CC</sub> I <sub>OUT</sub> =0V	4.3	-100		100	-500	500	nA	
I <sub>CCT</sub>	Increase in I <sub>CC</sub> Current	V <sub>IN</sub> =1.8V	4.3		7	12		15	μA	
ICCT	per Control Voltage	V <sub>IN</sub> =2.6V	4.3		3	6		7	μΛ	

#### Notes:

- 2. On resistance is determined by the voltage drop between A and B pins at the indicated current through the switch.
- Δ R<sub>ON</sub>=R<sub>ON max</sub> R<sub>ON min</sub> measured at identical V<sub>CC</sub>, temperature and voltage.
   Flatness is defined as the difference between the maximum and minimum value of on resistance over the specified range of conditions.

# **AC Electrical Characteristics**

Typical values are at 25°C unless otherwise specified.

Symbol	Parameter	Condition	V <sub>cc</sub>	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85ºC		Unit	Figure
				Min.	Тур.	Max.	Min.	Max.		
		nB0 or nB1=1.5V	3.6 to 4.3			50		60		
$t_{\text{ON}}$	Turn-On Time	R <sub>L</sub> =50Ω, C <sub>L</sub> =35pF	2.7 to 3.6			65		75	ns	Figure 8
			2.3 to 2.7			80		90		
		nB0 or nB1=1.5V	3.6 to 4.3			32		40		
t <sub>OFF</sub>	Turn-Off Time	$R_L=50\Omega$ , $C_L=35pF$	2.7 to 3.6			42		50	ns	Figure 8
			2.3 to 2.7			52		60		
		nB0 or nB1=1.5V	3.6 to 4.3		12					
$t_{BBM}$	t <sub>BBM</sub> Break-Before- Make Time	R <sub>L</sub> =50Ω, C <sub>L</sub> =35pF	2.7 to 3.6		15				ns	Figure 9
			2.3 to 2.7		20					
	$egin{array}{c} C_{L} = 100 pF, \\ V_{GEN} = 0V, R_{GEN} = 0\Omega \end{array}$ 3.6 to 4.3									
Q Charge Injection	$C_L=100pF,$ $V_{GEN}=0V,$ $R_{GEN}=0\Omega$	2.7 to 3.6		10		Y.		рС	Figure 11	
		$C_L=100pF,$ $V_{GEN}=0V,$ $R_{GEN}=0\Omega$	2.3 to 2.7		8					
1	7		3.6 to 4.3		-75					
OIRR	Off Isolation f=100KHz,	f=100KHz, R <sub>L</sub> =50Ω,C <sub>L</sub> =5pF	2.7 to 3.6		-75			Ų	dB	Figure 10
		Π[-3012,0[-3β]	2.3 to 2.7		-75					
			3.6 to 4.3		-75					
Xtalk	Crosstalk	$f=100KHz$ , $R_L=50\Omega$ , $C_L=5pF$	2.7 to 3.6		-75				dB	Figure 10
		St-spi	2.3 to 2.7		-75					
BW	-3dB Bandwidth	R <sub>L</sub> =50Ω	2.3 to 4.3		85			_1	MHZ	Figure 13
THD Total Harmonic Distortion	$R_L$ =32 $\Omega$ , $V_{IN}$ =2 $V_{PP}$ , f=20 to 20kHZ	3.6 to 4.3		0.02					7	
		$R_L$ =32 $\Omega$ , $V_{IN}$ =2 $V_{PP}$ , f=20 to 20kHZ	2.7 to 3.6		0.02		/		%	Figure 14
		$R_L$ =32 $\Omega$ , $V_{IN}$ =2 $V_{PP}$ , $f$ =20 to 20kHZ	2.3. to 2.7		0.02					

# Capacitance

Symbol	Parameter	Condition	V <sub>cc</sub>	T <sub>A</sub> = +25ºC Typical	Unit	Figure
C <sub>IN</sub>	Control Pin Input Capacitance	f=1MHZ	0	1.5	pF	Figure 8
C <sub>OFF</sub>	B Port Off Capacitance	f=1MHZ	3.3	32	pF	Figure 8
C <sub>ON</sub>	A Port On Capacitance	f=1MHZ	3.3	118	pF	Figure 8

# **Typical Applications**

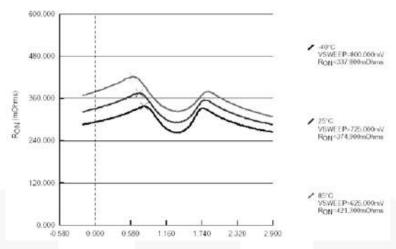


Figure 5.  $R_{ON}$  at 2.7V  $V_{CC}$ 

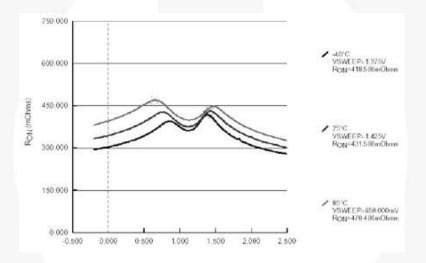
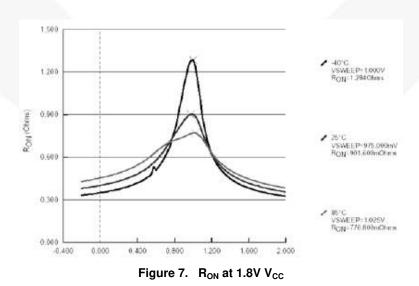
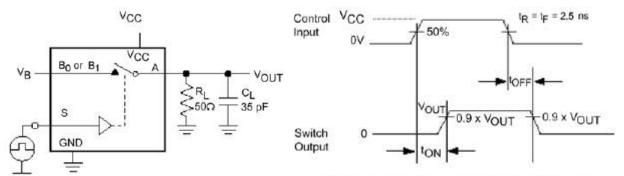


Figure 6.  $R_{ON}$  at 2.3V  $V_{CC}$ 



# **AC Loadings and Waveforms**



C<sub>L</sub> includes Fixture and Stray Capacitance

Logic Input Waveforms Inverted for Switches that have the Opposite Logic Sense

Figure 8. Turn-On / Turn-Off Timing

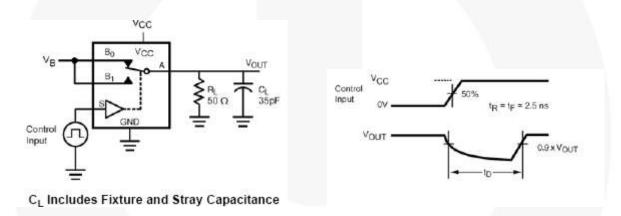


Figure 9. Break-Before-Make Timing

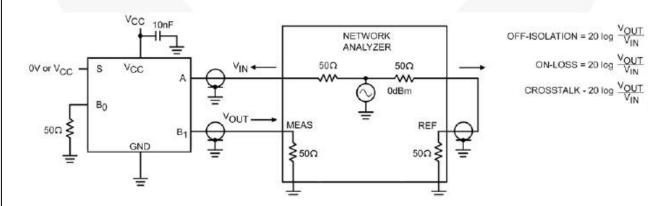


Figure 10. Off Isolation and Crosstalk

# AC Loadings and Waveforms (Continued)

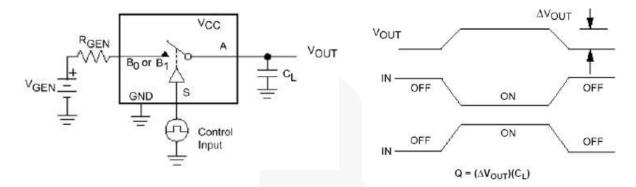


Figure 11. Charge Injection

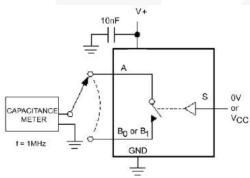


Figure 12. On / Off Capacitance Measurement Setup

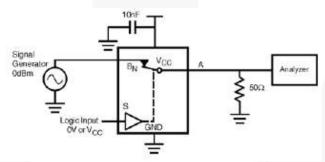


Figure 13. Bandwidth

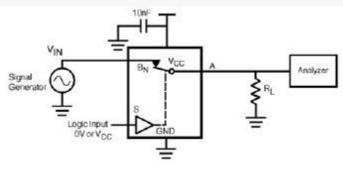
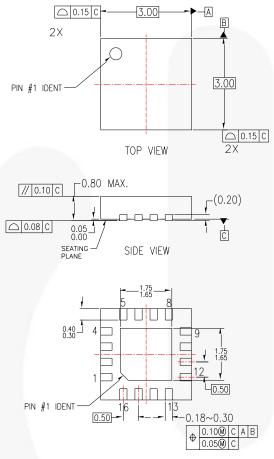


Figure 14. Harmonic Distortion

# **Package Dimensions**



(1.75) (3.30) (2.16) (3.30) (3

RECOMMENDED LAND PATTERN

BOTTOM VIEW

#### NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-220, VARIATION WEED-Pending, DATED pending
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- D. DIMENSIONS ARE EXCLUSIVE OF BURS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

MLP16BrevB

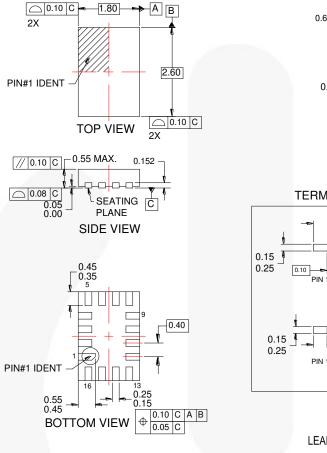
#### Figure 15. 16-Lead, Molded Leadless Package (MLP), JEDEC MO-220 3x3mm Square

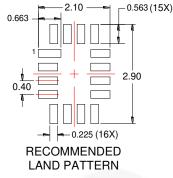
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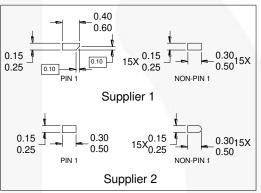
For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: http://www.fairchildsemi.com/packaging/3x3MLP16 Pack TNR.pdf.

## **Package Dimensions**



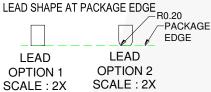


#### TERMINAL SHAPE VARIANTS



# NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY.
- E. DRAWING FILENAME: MKT-UMLP16Arev4.
- F. TERMINAL SHAPE MAY VARY ACCORDING TO PACKAGE SUPPLIER, SEE TERMINAL SHAPE VARIANTS.



#### Figure 16. 16-Lead, Ultrathin Molded Leadless Package (UMLP)

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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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